IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			der both	This docume level parts, the	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1					Form Type Distribute					ous Materia	ials and Mfg Information				
Supplier	· Information														
Company name*			Company unique ID			ī	Unique ID Authority					Response Date*			
nsemi												2025-06-06			
Contact N	ame		Title - Contact]	Phone - Contact*					Email - Contact*			
Product-E	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorize	d Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version Manufactur		Manufacturii	ng Site	W	eight*	UOM	Unit Type	
		NCV427	5CDS33R4G	3.3V/450mA LDO			2025-06-06					16	517.9136	mg	Each
Aanufa	cturing Proccess Informa	ation												·	·
	Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	TD-020 MSL Rating Peak Process Body Temperature Man			ure Max Tin	ne at Peak	Temperatu	re Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30		second	3			
Comments															
evel 1 - m	aximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more i	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	A	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	851.27	mg	В	Nickel (Ni)	7440-02-0		2.5538	mg
			Supplier	Copper (Cu)	7440-50-8		848.7162	mg
Mold Compound-Black	727.2536			Epoxy resin	proprietary data		36.3627	mg
			Supplier	Phenolic Resin	Proprietary Data		36.3627	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		14.5451	mg
			Supplier	Carbon Black (C)	1333-86-4		3.6363	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		636.3469	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg